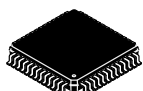


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

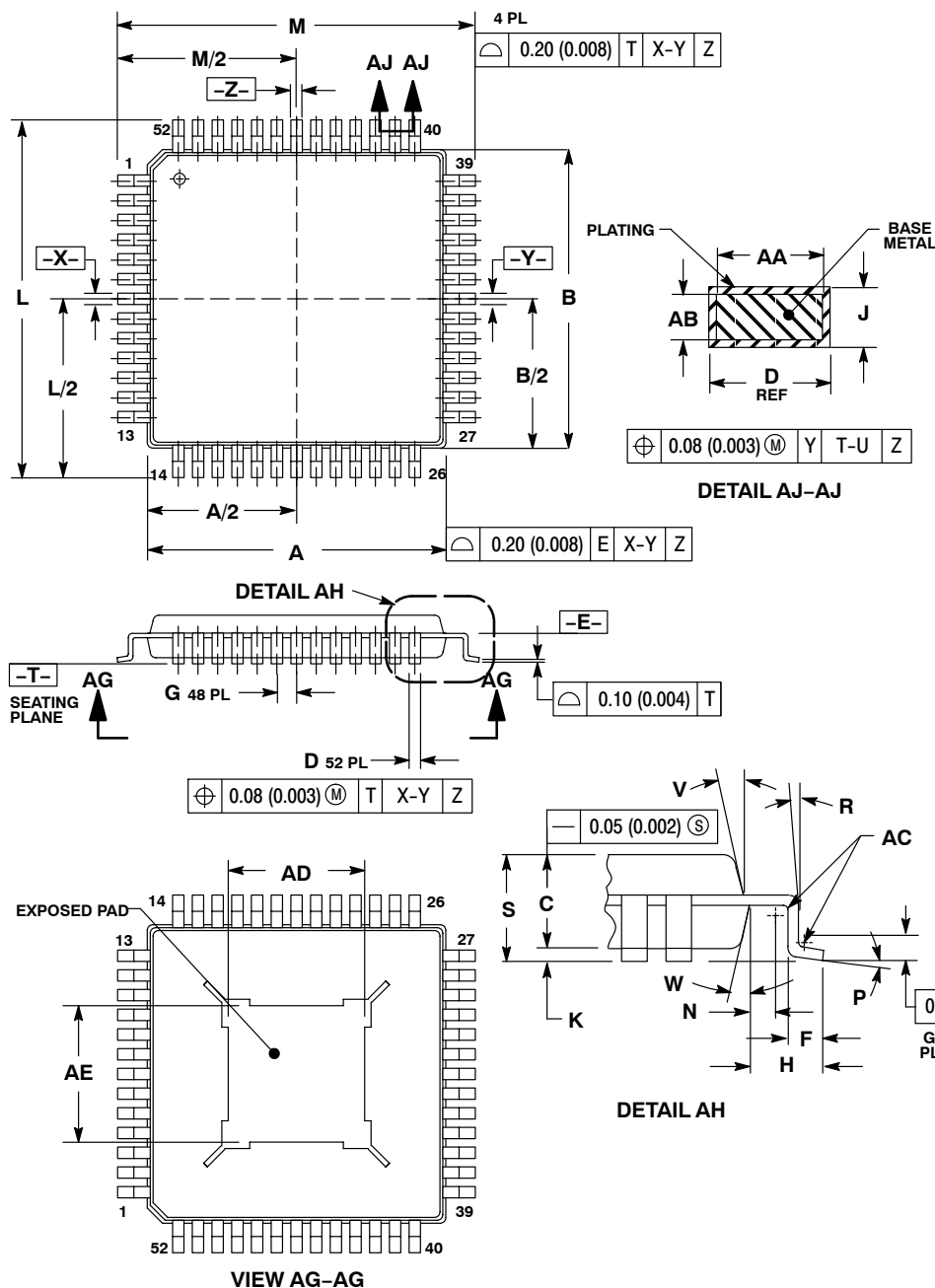
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SCALE 1:1

LQFP 52
CASE 848H-01
ISSUE B

DATE 16 FEB 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MM.
3. DATUM PLANE "E" IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING PLANE.
4. DATUM "X", "Y" AND "Z" TO BE DETERMINED AT DATUM PLANE DATUM "E".
5. DIMENSIONS M AND L TO BE DETERMINED AT SEATING PLANE DATUM "T".
6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE "E".
7. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM D DIMENSION BY MORE THAN 0.08 (0.003). DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 (0.003).

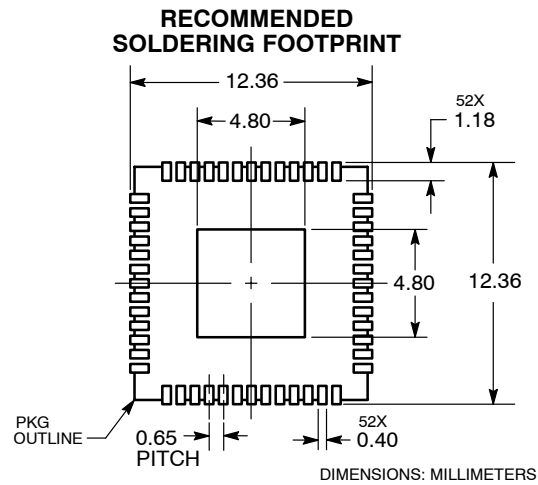
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.00 BSC		0.394 BSC	
B	10.00 BSC		0.394 BSC	
C	1.30	1.50	0.051	0.059
D	0.22	0.40	0.009	0.016
F	0.45	0.75	0.018	0.030
G	0.65 BSC		0.026 BSC	
H	1.00 REF		0.039 BSC	
J	0.09	0.20	0.004	0.008
K	0.05	0.20	0.002	0.008
L	12.00 BSC		0.472 BSC	
M	12.00 BSC		0.472 BSC	
N	0.20 REF		0.008 REF	
P	0°	7°	0°	7°
R	0°	---	0°	---
S	---	1.70	---	0.067
V	12° REF		12° REF	
W	12° REF		12° REF	
AA	0.20	0.35	0.008	0.014
AB	0.07	0.16	0.003	0.006
AC	0.08	0.20	0.003	0.008
AD	4.58	4.78	0.180	0.188
AE	4.58	4.78	0.180	0.188

**RECOMMENDED
SOLDERING FOOTPRINT
ON PAGE 2**

xx = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

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